

Abstract

This invention relates to circuit boards and methods of fabricating circuit boards. A circuit board includes a core layer and a surface layer. The core layer includes a number of fibers and the surface layer has a thickness that is between about 10% and about 30% of the circuit board thickness. Including fibers in the core layer increases the strength of the circuit board. The surface layer is essentially free of fibers and relatively thick. The thickness of the surface layer inhibits the formation of cracks in the circuit board, which improves the reliability of circuits and systems coupled to the circuit board.

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